

IN THE CLAIMS:

1-20. (Cancelled)

21. (Currently Amended) A method of forming an orientation film on a substrate comprising:

providing a substrate on a stage, said substrate facing downwardly from a bottom-facing surface of said stage;

positioning a slit coater having a slit nozzle adjacent to and spaced from the substrate a distance corresponding to the desired thickness of said orientation film ; and

spraying an orientation material having a surface tension on the substrate through the slit nozzle of the slit coater while maintaining the surface tension of the orientation material, said orientation material being coated on said stage at a speed which maintains said surface tension, and

patterning an orientation pattern at a predetermined portion of the orientation material using a laser beam.

22. (Previously Presented) The method of claim 21, wherein the thickness of the orientation material ranges from about 0.8 μm to about 1.0 μm .

23. (Previously Presented) The method of claim 21, wherein the slit nozzle is maintained at a predetermined distance from the substrate.

24-25. Cancelled.

26. (Currently Amended) The method of claim 21 25, wherein the predetermined portions of the orientation material include a spraying surface of the orientation material.

27. (Currently Amended) The method of claim 21 24, wherein the laser is an eximer laser.

28-31. Cancelled.

32. (Currently Amended) The method of claim 21 28, further comprising rubbing the orientation material.

33. (Previously Presented) The method of claim 32, wherein the step of rubbing is performed after spraying.

34. (Previously Presented) The method of claim 32,
wherein the rubbing is performed after forming an orientation
pattern.

35-38. Cancelled.